



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-10-14
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	AMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TS3330ACR	HVW9*U1L7AC5	A	ZS1A	2024-10-14
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	6	mg	Each	ECOPACK® 2
Identity	Authority			
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
CHP	2 x 1.29	3	gull wing
Comment			
Comment	W9 SOT 323 - 3 LEADS		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 17th Nov 2023	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	false		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	true		
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.032	alloy	5333

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
QUERY	Response			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-27th June 2024	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
QUERY	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document.						Mfr Item Name	HW9*U1L7ACS		6.0000		5000001.0	999999.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	0.375	mg	supplier	die	Silicon(Si)	7440-21-3		0.351	mg	936000	58500				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.005	mg	13333	833				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.004	mg	10667	667				
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.001	mg	2667	167				
				supplier	passivation	Silicon oxide	7631-86-9		0.009	mg	24000	1500				
				supplier	polymer coating	polyimide	proprietary		0.005	mg	13333	833				
				supplier	alloy	Copper (Min 97%)	7440-50-8		2.401	mg	960400	400167				
Leadframe	M-004 Copper and its alloys	2.500	mg	supplier	alloy	Phosphorus (0.015 – 0.150%)	7723-14-0		0.002	mg	800	333				
				supplier	alloy	Zinc (0.05 – 0.2%)	7440-66-6		0.003	mg	1200	500				
				supplier	alloy	Iron (2.1 – 2.6%)	7439-89-6		0.059	mg	23600	9833				
				supplier	alloy	Nickel plating (0.122 – 2.408%)	7440-02-0		0.032	mg	12800	5333				
				supplier	alloy	Palladium (0.003 – 0.198%)	7440-05-3		0.003	mg	1200	500				
				Die attach	M-011 Other inorganic materials	0.043	mg	supplier	glue	Aluminium oxide (90 – 60%)	1344-28-1		0.019	mg	450000	3225
								supplier	glue	Ethyl acetate (10 – 30%)	112-15-2		0.009	mg	200000	1433
				supplier	glue	Epoxy resin (10 – 30%)	Proprietary		0.008	mg	180000	1290				
				supplier	glue	Bisphenol A (epichlorohydrin), epoxy resin (1 – 1	25068-38-6		0.002	mg	55000	394				
				supplier	glue	Dapsone (1 – 10%)	80-08-0		0.002	mg	55000	394				
				supplier	glue	Silane, dichlorodimethyl-,reaction products with	68611-44-9		0.002	mg	55000	394				
				supplier	glue	Aminopropyltriethoxysilane (0.1 – 1%)	919-30-2		0.0002	mg	5000	36				
Bonding wires	M-008 Precious metals	0.037	mg	supplier	wire	Au	7440-57-5		0.037	mg	1000000	6167				
Encapsulation	M-011 Other inorganic materials	3.045	mg	supplier	mold compound	Solid Epoxy Resin-1 (0.1 – 11%)	Proprietary		0.061	mg	20099	10200				
				supplier	mold compound	Solid Epoxy Resin-2 (0.1 – 11%)	Proprietary		0.061	mg	20099	10200				
				supplier	mold compound	Phenol resin (2 – 12%)	Proprietary		0.122	mg	40197	20400				
				supplier	mold compound	Amorphous Silica (85 – 95%)	60676-86-0		2.708	mg	889458	451400				
				supplier	mold compound	Carbon Black (< 1%)	1333-86-4		0.015	mg	5025	2550				
				supplier	mold compound	Crystalline silica (< 5%)	14808-60-7		0.077	mg	25123	12750				